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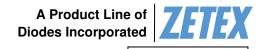












ZXTC2045E6

30V COMPLEMENTARY MEDIUM POWER TRANSISTOR IN SOT26

Features

- NPN + PNP Combination
- BV_{CEO} > 30 (-30)V
- BV_{CEV} > 40 (-40)V
- I_{CM} = 5 (-5)A Peak Pulse Current
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Description

Advanced process capability is used to achieve this high performance device. Combining NPN and PNP transistors, the SOT26 package provides a compact solution for the intended applications.

Mechanical Data

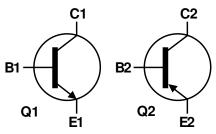
- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound;
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads; Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.015 grams (Approximate)

Applications

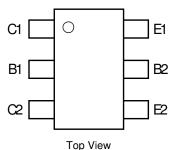
- MOSFET and IGBT Gate Driving
- Motor Drive







Device Symbol



Pin-Out

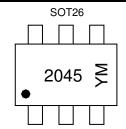
Ordering Information (Notes 4 & 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTC2045E6TA	AEC-Q101	2045	7	8	3,000
ZXTC2045E6QTA	Automotive	2045	7	8	3,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/ for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- Automotive products are AEC-Q101 qualified and PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally
 the same, except where specified.
- 5. For packaging details, go to our website at http://www.diodes.com

Marking Information



2045 = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: C = 2015) M or \overline{M} = Month (ex: 9 = September)

Date Code Key

Ye	ear	201	5	2016	2017	2018	2019	2020	202	1 20)22	2023	2024	2025
Co	de	С		D	Е	F	G	Н		,	J	K	L	М
	Month	1	Jar	n Fel	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
	Code		1	2	3	4	5	6	7	8	9	0	N	D



Absolute Maximum Ratings - Q1 (NPN Transistor) (@TA = +25 ℃, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	40	V
Collector-Emitter Voltage	V _{CEV}	40	V
Collector-Emitter Voltage	V _{CEO}	30	V
Emitter-Base Voltage	V_{EBO}	7	V
Continuous Collector Current	lc	1.5	Α
Peak Pulsed Collector Current	Ісм	5	Α
Base Current	I _B	1	A

Absolute Maximum Ratings - Q2 (PNP Transistor) (@TA = +25 ℃, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-40	V
Collector-Emitter Voltage	V _{CEV}	-40	V
Collector-Emitter Voltage	V _{CEO}	-30	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current	Ic	-1.5	Α
Peak Pulsed Collector Current	I _{CM}	-5	Α
Base Current	I _B	-1	Α

Thermal Characteristics (@T_A = +25 °C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
	(Notes 6 & 10)		0.7 5.6		
	(Notes 7 & 10)		0.9 7.2		
Power Dissipation Linear Derating Factor	(Notes 7 & 11)	P_D	1.1 8.8	W mW/℃	
	(Notes 8 & 10)		1.1 8.8		
	(Notes 9 & 10)		1.7 13.6		
	(Notes 6 & 10)		179	_	
	(Notes 7 & 10)		139		
Thermal Resistance, Junction to Ambient	(Notes 7 & 11)	$R_{ heta JA}$	113	0C AM	
	(Notes 8 & 10)		113	°C/W	
	(Notes 9 & 10)		73	1	
Thermal Resistance, Junction to Lead	(Note 12)	$R_{ hetaJL}$	95.50		
Operating and Storage Temperature Range		TJ, T _{STG}	-55 to +150	.€	

ESD Ratings (Note 13)

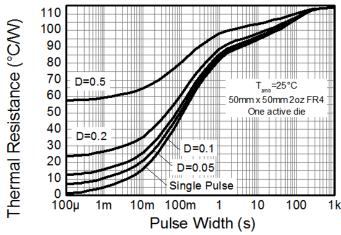
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Notes: 6. For a device surface mounted on 15mm x 15mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

- 7. Same as Note 6, except the device is surface mounted on 25mm x 25mm 1oz copper.
- 8. Same as Note 6, except the device is surface mounted on 50mm x 50mm 2oz copper.
- 9. Same as Note 8, except the device is measured at t < 5 seconds.
- 10. For device with one active die, both collectors attached to a common heatsink.
- 11. For device with two active die running at equal power, split heatsink 50% to each collector.
- 12. Thermal resistance from junction to solder-point (at the end of the collector lead).
- 13. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



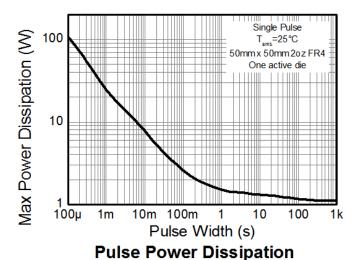
Thermal Characteristics and Derating Information



2.0 50mm x 50mm 2oz FR4 Max Power Dissipation (W) One active die t<5secs 25mm x 25mm 1oz FR4 1.5 Two active die 50mm x 50mm 2oz FR4 One active die 1.0 25mm x 25mm 1oz FR4 One active die 0.5 15mm x 15mm 1oz FR4 One active die 20 40 80 100 Temperature (°C)

Derating Curve







Electrical Characteristics - Q1 (NPN Transistor) (@TA = +25 ℃, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV_{CBO}	40	-		V	$I_C = 100 \mu A, I_E = 0$
Collector-Emitter Breakdown Voltage	BV _{CEV}	40	-	_	V	$I_C = 1\mu A$, $0.25V > V_{BE} > 1.0V$
Collector-Emitter Breakdown Voltage (Note 14)	BV _{CEO}	30	-	_	V	$I_C = 10mA, I_B = 0$
Emitter-Base Breakdown Voltage	BV _{EBO}	7	8.3	_	V	$I_E = 100 \mu A, I_C = 0$
Collector Cut-Off Current	I _{CBO}	_	<1	20	nA	$V_{CB} = 32V$
Collector Cut-Off Current	I _{CES/R}	_	<1	20	nA	$V_{CE} = 16V, R \le 1k\Omega$
Emitter Cut-Off Current	I _{EBO}	_	<1	20	nA	$V_{EB} = 6V$
ON CHARACTERISTICS (Note 14)						
DC Current Gain	h _{FE}	180	300	500		$I_C = 100 \text{mA}, V_{CE} = 2V$
Collector-Emitter Saturation Voltage	V _{CE(sat)}		_	375	mV	$I_C = 750 \text{mA}, I_B = 15 \text{mA}$
Base-Emitter Saturation Voltage	V _{BE(sat)}	_	_	1,200	mV	$I_C = 750 \text{mA}, I_B = 15 \text{mA}$
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C_obo		9	20	рF	$V_{CB} = 10V, f = 1.0MHz$
Current Gain-Bandwidth Product	f⊤		265		MHz	V _{CE} = 10V, I _C = 50mA, f = 100MHz
Delay Time	t _d	_	10	_	ns	
Rise Time	t _r	_	12		ns	V _{CC} = 10V, I _C = 1A
Storage Time	ts	_	185	_	ns	$I_{B1} = -I_{B2} = 50 \text{mA}$
Fall Time	t _f	_	45	_	ns	

Electrical Characteristics - Q2 (PNP Transistor) (@T_A = +25 ℃, unless otherwise specified.)

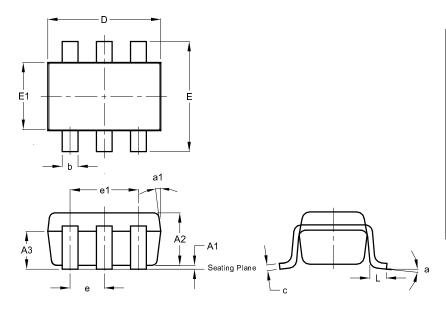
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV _{CBO}	-40	-	_	٧	$I_C = -100 \mu A, I_E = 0$
Collector-Emitter Breakdown Voltage	BV _{CEV}	-40	-	_	V	$I_C = -1\mu A$, $0.25V < V_{BE} < 1.0V$
Collector-Emitter Breakdown Voltage (Note 14)	BV _{CEO}	-30	-		٧	$I_C = -10 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	-8.3	_	V	$I_E = -100 \mu A, I_C = 0$
Collector Cut-Off Current	I _{CBO}	_	<-1	-20	nA	V _{CB} = -32V
Collector Cut-Off Current	I _{CES/R}	_	<-1	-20	nA	$V_{CE} = -16V, R \le 1k\Omega$
Emitter Cut-Off Current	I _{EBO}	_	<-1	-20	nA	V _{EB} = -6V
ON CHARACTERISTICS (Note 14)						
DC Current Gain	h _{FE}	180	300	500		$I_C = -100 \text{mA}, V_{CE} = -2 \text{V}$
Collector-Emitter Saturation Voltage	V _{CE(sat)}	_		-375	mV	$I_C = -750 \text{mA}, I_B = -15 \text{mA}$
Base-Emitter Saturation Voltage	V _{BE(sat)}	_		-1,200	mV	$I_C = -750 \text{mA}, I_B = -15 \text{mA}$
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C_{obo}	_	9	20	рF	$V_{CB} = -10V, f = 1.0MHz$
Current Gain-Bandwidth Product	f _T	_	195		MHz	$V_{CE} = -10V$, $I_{C} = -50mA$, $f = 100MHz$
Delay Time	t _d	_	16		ns	
Rise Time	t _r	_	11		ns	$V_{CC} = -10V, I_{C} = -1A$
Storage Time	ts	_	220		ns	$I_{B1} = -I_{B2} = -50 \text{mA}$
Fall Time	t _f		31	_	ns	

Note: 14. Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.



Package Outline Dimensions

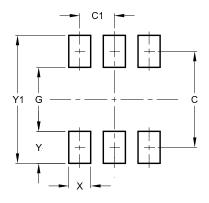
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SOT26						
Dim	Min	Max	Тур			
A1	0.013	0.10	0.05			
A2	1.00	1.30	1.10			
A 3	0.70	0.80	0.75			
b	0.35	0.50	0.38			
С	0.10	0.20	0.15			
D	2.90	3.10	3.00			
е	-	-	0.95			
e1	-	1	1.90			
Е	2.70	3.00	2.80			
E1	1.50	1.70	1.60			
L	0.35	0.55	0.40			
а	-	-	8°			
a1	-	-	7°			
All	Dimen	sions	in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	2.40
C1	0.95
G	1.60
Х	0.55
Υ	0.80
Y1	3.20





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